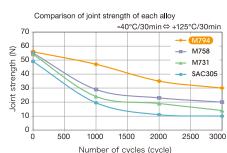


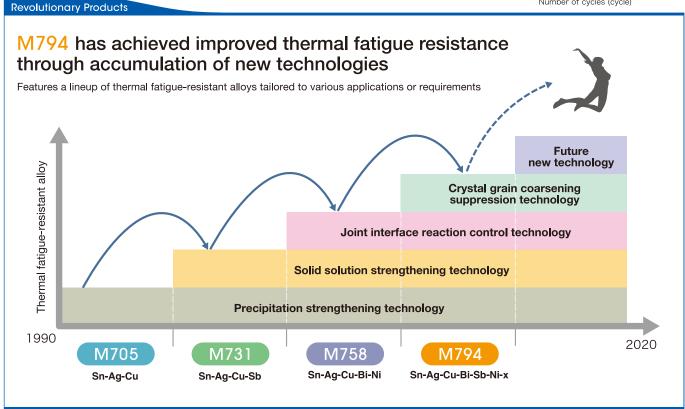
Solder Alloy M794

Thermal Fatigue Resistant Alloy Developed with New Metal Bonding Mechanism

Features

- M794-the newest thermal fatigue-resistant alloy that exhibits little deterioration due to thermal fatigue
- M758-general-purpose thermal fatigue-resistant alloy for SMT
- M731-a thermal fatigue-resistant alloy best suited for flow soldering

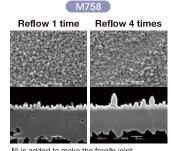




Joint surface reaction control technology

Prevents changes of the fracture mode and enhances the joint strength by controlling the joint interface reaction

Reflow 1 time Reflow 4 times



Ni is added to make the fragile joint interface thin, fine and smooth to ensure strength

Crystal grain coarsening suppression technology

Technology to suppress coarsening of the Sn structure after thermal cycle tests can prevent the lowering of strength and generation of cracks

